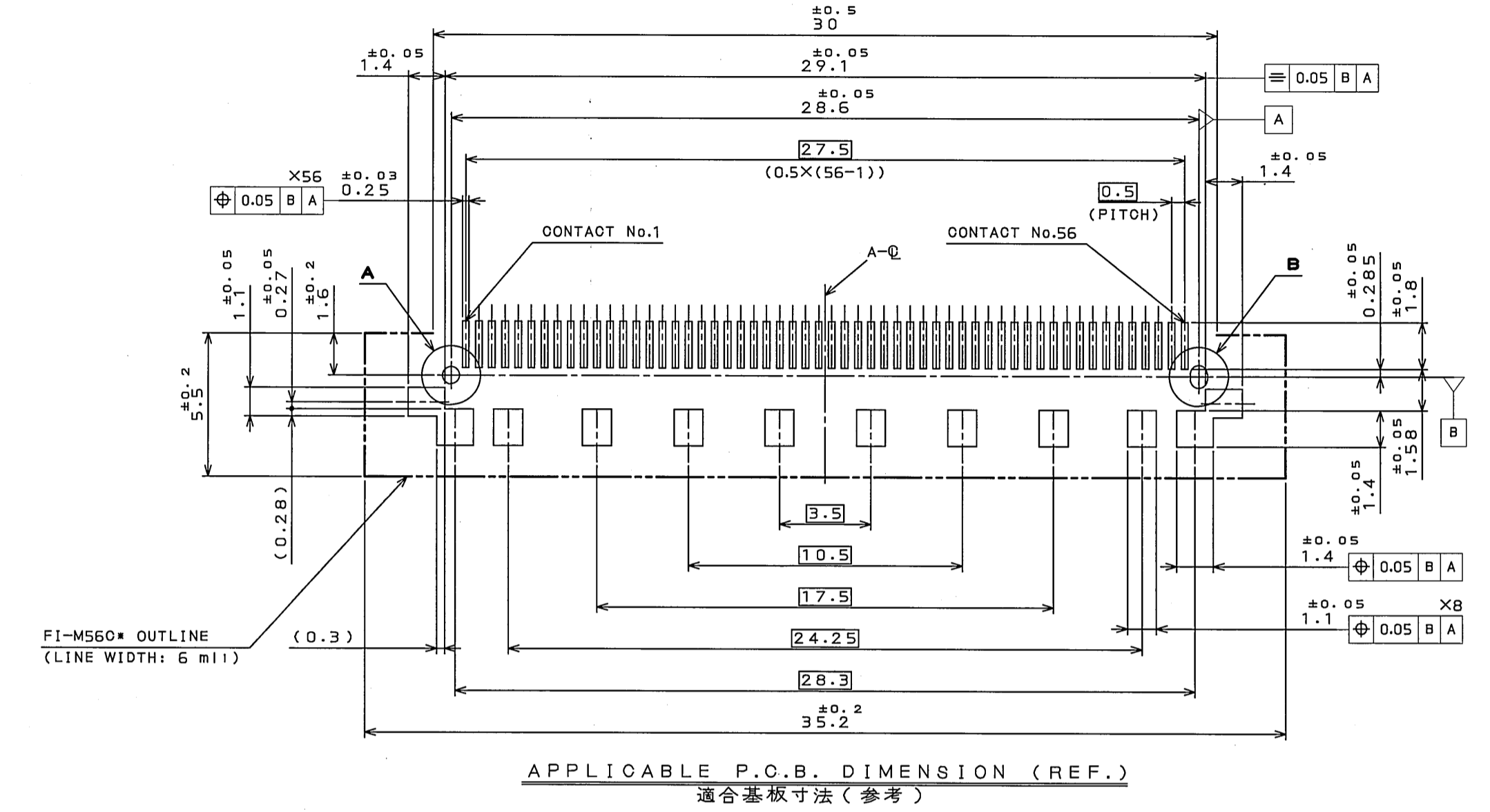
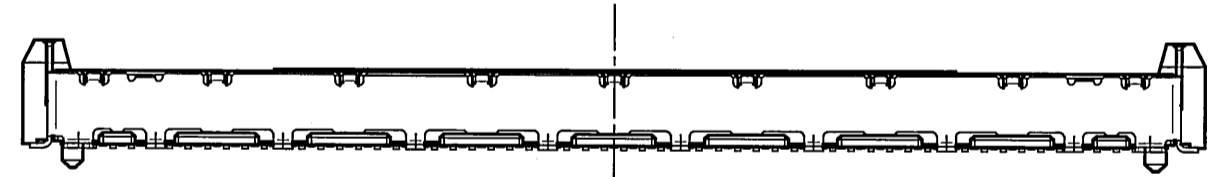
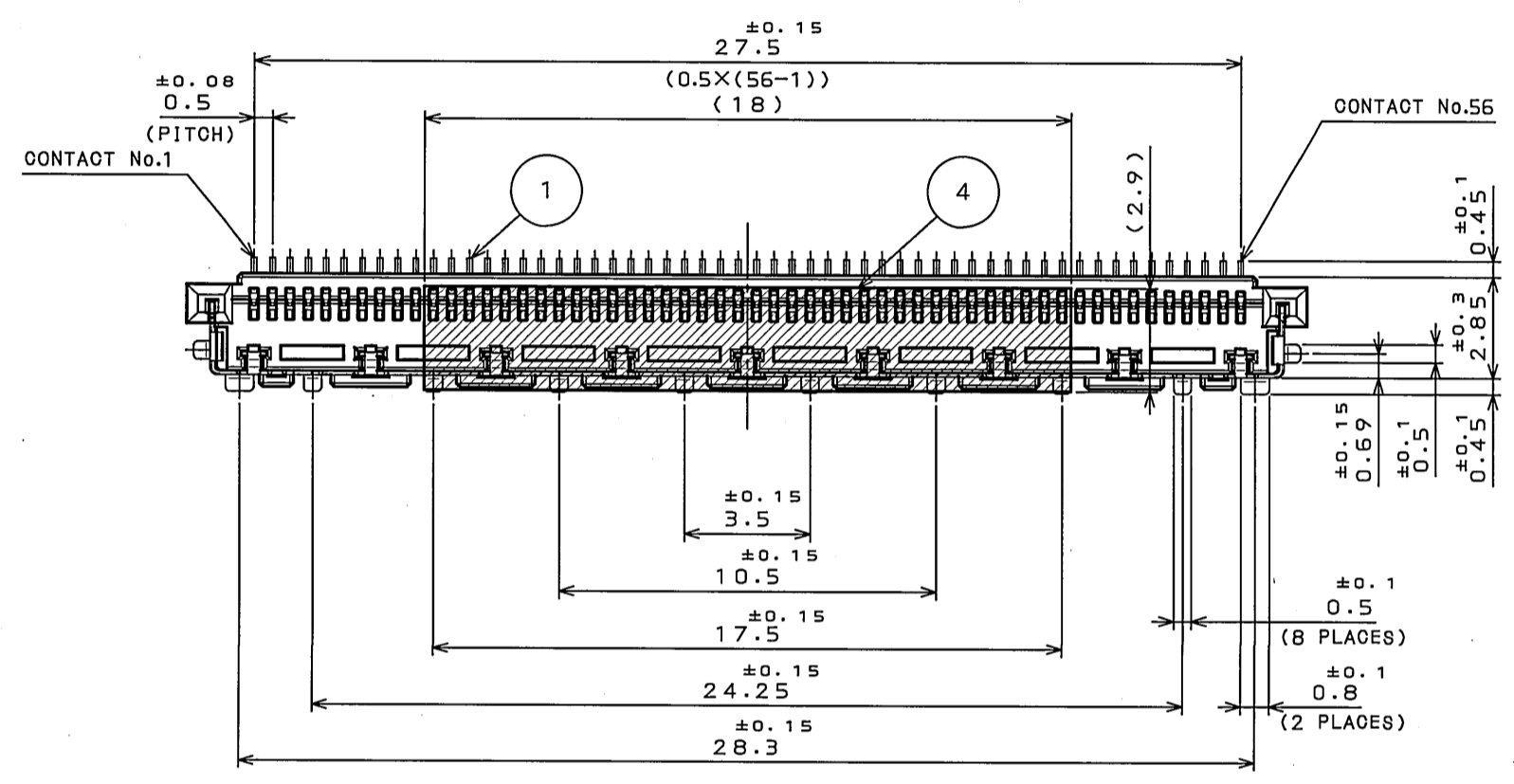
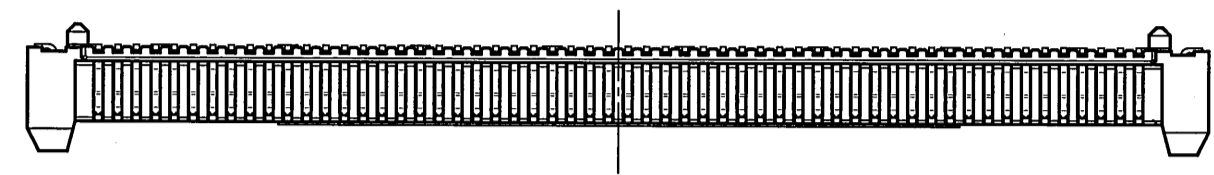
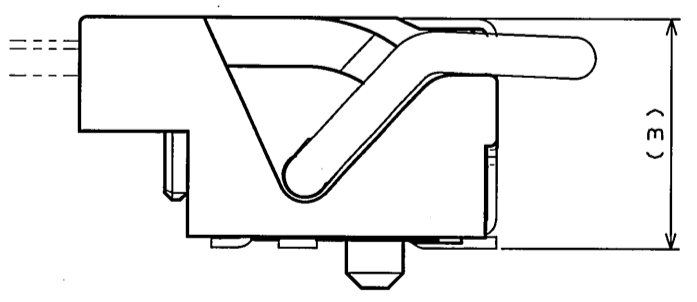
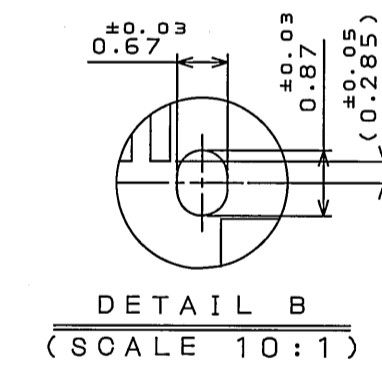
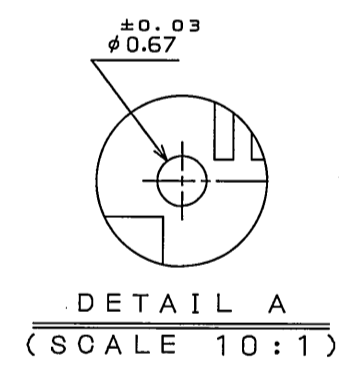
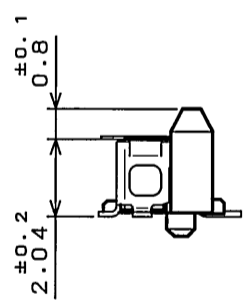


版数 REV.	年月日 DATE	DON NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.



APPLICABLE P.C.B. DIMENSION (REF.)
適合基板寸法(参考)



MATED CONDITION (REF.)
嵌合状態図(参考)

NOTE1. COPLANALITY OF SMT TERMINAL IS 0.1 MAX.
注1. コンタクトのコプラナリティは0.1以下とする。

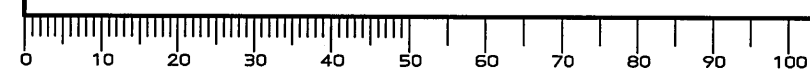
TABLE 1

CONTACT AREA 接触部	GOLD(0.3μm MIN.) OVER NICKEL Ni上Au 0.3μm以上
TERMINAL AREA 端子部	GOLD FLASH OVER NICKEL Ni上Auフラッシュ

NO.	DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
4	HEAT-RESISTING TAPE	1	PI.		
3	SHELL	1	STAINLESS STEEL	TIN PLATING OVER NICKEL	
2	INSULATOR	1	HEAT-RESISTING PLASTIC		UL94V-0 COLOR: BLACK
1	CONTACT	56	COPPER ALLOY	REFER TO TABLE1	

仕様書(SPECIFICATION) JACS-10410-*	第1版(ORIGINAL DATE) 28.Feb.2007	尺(SCALE) 5:1	シリーズ(SERIES) FI-M	日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.
公差(GENERAL TOLERANCE)	製図 DR.	名称(TITLE)	FI-M56SB1	図面番号(DRAWING NO.) SJ107450
寸法(DIMENSION)	担当 CHK. M.SASAKI	RECEPTACLE		
角度(ANGLES)	承認 APPD. K.Hsatori	質量(MASS)		

DOF-0-213F(05.08)



SIZE A2